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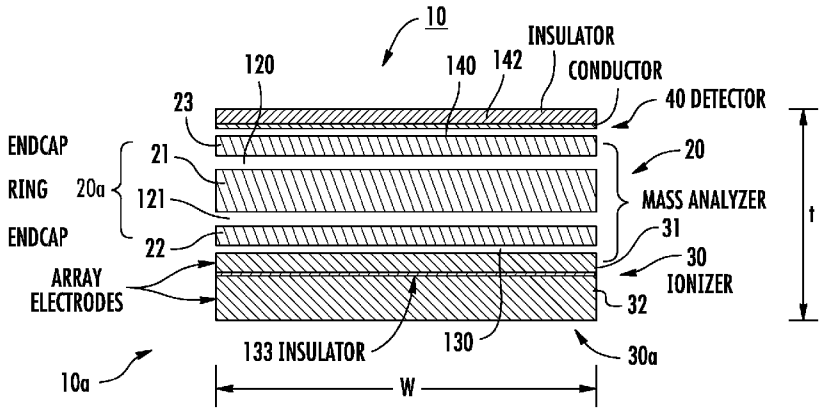


FIG. 1A

(57) Abstract: Mass spectrometry systems or assemblies therefore include an ionizer that includes at least one planar conductor, a mass analyzer with a planar electrode assembly, and a detector comprising at least one planar conductor. The ionizer, the mass analyzer and the detector are attached together in a compact stack assembly. The stack assembly has a perimeter that bounds an area that is between about 0.01 mm^2 to about 25 cm^2 and the stack assembly has a thickness that is between about 0.1 mm to about 25 mm.

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MICROSCALE MASS SPECTROMETRY SYSTEMS, DEVICES AND RELATED METHODS

Related Applications

[0001] This application claims the benefit of and priority to U.S. Patent Application Serial Number 13/804,911, filed March 14, 2013, the contents of which are hereby incorporated by reference as if recited in full herein.

Statement of Government Support

[0002] This invention was made with government support under the Department of Energy grant number **DE-AC05-00OR22725**. The United States government has certain rights in the invention.

Field of the Invention

[0003] This invention is related to mass spectrometry and is particularly suitable for portable high pressure mass spectrometers.

Background of the Invention

[0004] Mass spectrometry is a powerful tool for indentifying and quantifying gas phase molecules. A mass spectrometry system has three fundamental components: an ion source, a mass analyzer and a detector. These components can take on different forms depending on the type of mass analyzer. Interest in portable mass spectrometry (MS) has increased due to potential uses where rapid *in situ* or field measurements may be of value. Conventional mass spectrometers are unsuitable for these situations because of their large size, weight, and power consumption (SWaP). *See, e.g.*, Whitten et al., *Rapid Commun. Mass Spectrom.* **2004**, *18*, 1749-52.

[0005] There remains a need for portable, compact and light-weight mass spectrometers for chemical monitoring and analysis.

Summary of Embodiments of the Invention

[0006] Embodiments of the invention are directed to configurations of fundamental mass spectrometry components into compact packages to reduce size and weight of the overall system.

[0007] Embodiments of the invention provide systems, methods and devices configured to provide compact, light-weight high pressure mass spectrometers that may

facilitate field use.

[0008] Some embodiments are directed to assemblies for a mass spectrometry system. The assemblies include: (a) an ionizer including at least one planar conductor; (b) a mass analyzer including a planar electrode assembly; and (c) a detector including at least one planar conductor. The ionizer, the mass analyzer and the detector are attached together in a compact planar stacked assembly. The stacked assembly has a perimeter that bounds an area that is between about 0.01 mm^2 to about 25 cm^2 and has a thickness that is between about 0.1 mm to about 25 mm.

[0009] The ionizer, detector and mass analyzer can be configured as respective cooperating ionizer arrays, detector arrays and mass analyzer arrays.

[0010] The detector at least one planar conductor can include a Faraday cup electrode.

[0011] The Faraday cup electrode, where used, can include a thin conductive film on a substrate.

[0012] The ionizer planar conductor can be configured to cooperate with the detector to define a collection electrode for the Faraday cup.

[0013] The Faraday cup electrode can include a conductive layer with a substantially continuous conductive surface.

[0014] The mass analyzer can include an ion trap. The detector can be configured with the at least one planar electrode to include a Faraday cup electrode that has a conductive layer in a shaped pattern of conductive regions that overlie and align with corresponding apertures in an adjacent electrode of the ion trap.

[0015] The substrate of the Faraday cup electrode can be a semiconductor forming an integrated circuit. The conductive layer can include a single trace or strip that connects each conductive region to an electronic collector.

[0016] The ionizer can include a pair of planar conductors that define array electrodes separated by an insulator.

[0017] The mass analyzer can include an ion trap array. A first endcap electrode of the ion trap array can define one of the at least one planar electrode of the ionizer.

[0018] The assembly may include an Einzel lens comprising a plurality of spaced apart electrodes residing between the ionizer and the mass analyzer.

[0019] The mass analyzer can be a cylindrical ion trap. The Einzel lens electrodes can be configured as an array of lens apertures that align with corresponding apertures of the ion trap. The Einzel lens apertures can have a size that substantially correspond to an

aperture size of the ring electrode.

[0020] The assembly can include at least one planar grid that resides between either (or both if more than one grid) (i) the mass analyzer and the detector or (ii) the mass analyzer and the ionizer.

[0021] The assembly can include first and second planar grids, the first grid residing between the mass analyzer and the detector and the second grid residing between the mass analyzer and the ionizer.

[0022] The stacked assembly can include between 7-100 stacked conductive and insulating layers that form the mass analyzer, ionizer and detector.

[0023] The mass analyzer can include a planar ring electrode and first and second opposing planar endcap electrodes. The ion trap can have an aperture array of at least 10 spaced apart apertures with centers of adjacent apertures residing between about 1 μm to about 5000 μm apart.

[0024] The detector at least one planar electrode can include a conductor on an integrated circuit amplifier.

[0025] The mass analyzer can include a CIT with concentric arrays of apertures.

[0026] The CIT can include at least one mesh endcap.

[0027] The detector at least one planar conductor can include at least one of the following: a single conductor, a single conductor on an insulator, an array of conductors that are connected or addressable by an amplifier.

[0028] Other embodiments are directed to portable high-pressure mass spectrometers. The portable devices include a housing and at least one chamber inside the housing. A compact stacked assembly is held inside the chamber. The compact stacked assembly includes: (a) an ionizer comprising at least one planar conductor; (b) a mass analyzer comprising a planar electrode assembly; and (c) a detector comprising at least one planar conductor. The device also includes a drive RF power source in the housing in communication with the mass analyzer and a control circuit held by the housing configured to control activation and/or deactivation of the ionizer, the drive RF power source, and the detector. The compact stack assembly has a perimeter that bounds an area that is between about 0.1 mm^2 to about 25 cm^2 and has a thickness that is between about 0.1 mm to about 25 mm.

[0029] The mass analyzer can include an ion trap with a planar ring electrode and first and second opposing planar endcap electrodes. The ion trap can have an aperture array of at least 10 spaced apart apertures with centers of adjacent apertures residing between about 1

μm to about 5000 μm apart.

[0030] The mass spectrometer of Claim 21 can also optionally include an axial RF power source held inside the housing and electrically connected to the mass analyzer. The control circuit can be configured to control operation of the axial RF power source.

[0031] The mass spectrometer can include a pressurized buffer gas source in fluid communication with the housing for providing a buffer gas to the chamber.

[0032] The housing can be configured to controllably receive ambient air as buffer gas in the chamber.

[0033] The spectrometer can be configured to be a hand-held, light weight spectrometer having a weight between about 1-15 pounds, exclusive of a vacuum pump, and wherein the mass spectrometer chamber is a vacuum chamber that is configured to operate at high pressure of about 100 mTorr or greater.

[0034] The housing can be sized and configured as a handheld housing with a display and a user interface with a display providing a user interface (UI) or in communication with a UI.

[0035] The mass spectrometer can include an axial RF power source is configured to apply a low voltage axial RF input signal to an endcap electrode or between the two endcap electrodes of the mass analyzer during a mass scan.

[0036] The planar conductor of the detector can be configured as a Faraday cup electrode that comprises a conductive layer on a semiconductor substrate with a substantially continuous conductive surface.

[0037] The compact stacked assembly perimeter can bound an area that is between about 0.1 mm^2 to about 10 cm^2. The compact stacked assembly can have a thickness that is between about 0.1 mm to about 10 mm.

[0038] The compact stacked assembly can include between 7-100 stacked conductive and insulating layers that form the mass analyzer, ionizer and detector.

[0039] The compact stacked assembly can include at least one planar grid and at least one planar lens assembly.

[0040] The mass analyzer can be an ion trap. The at least one planar electrode of the detector can include a Faraday cup electrode that has a conductive layer in a shaped pattern of conductive regions that overlie and align with corresponding apertures in an adjacent electrode of the ion trap.

[0041] The conductive layer can have a single trace or strip that connects each conductive region to an electronic collector.

[0042] The ionizer can include a pair of planar conductors that define electrodes separated by an insulator.

[0043] The mass analyzer can include an ion trap. A first electrode of the ion trap can define one of the at least one planar electrode of the ionizer.

[0044] The mass spectrometer stacked assembly can also include an Einzel lens comprising a plurality of spaced apart electrodes residing between the ionizer and the mass analyzer.

[0045] The mass analyzer can be a cylindrical ion trap. The Einzel lens electrodes can include an array of lens apertures that align with corresponding apertures of the ion trap.

[0046] The compact stacked assembly can include at least one planar grid that resides between either (i) the mass analyzer and the detector or (ii) the mass analyzer and the ionizer.

[0047] The mass analyzer can include a CIT.

[0048] The CIT can include concentric arrays of apertures.

[0049] The CIT can include at least one mesh endcap.

[0050] The detector at least one planar conductor can include a conductor on an integrated circuit amplifier.

[0051] The mass analyzer can be a mass analyzer array, the ionizer can be an ionizer array and the detector can be a detector array.

[0052] At least one of the at least one ionizer planar conductor is configured to cooperate with the detector to define a collection electrode for a Faraday cup associated with the detector.

[0053] The mass spectrometer can be configured so that the ionizer, mass analyzer and detector operate at near isobaric conditions and at a pressure that is greater than 100 mTorr.

[0054] Still other embodiments are directed to methods of fabricating an assembly for a mass spectrometer system. The methods include: (a) providing a mass analyzer comprising an electrode assembly of planar electrodes; (b) providing a detector comprising a planar conductor; (c)providing an ionizer comprising planar conductive and insulating layers; and (d) stacking the mass analyzer electrode assembly, the detector and the ionizer together to form a stacked integral assembly having a perimeter that bounds an area between 0.01 mm^2 to 25 cm^2 and a stack thickness of between about 0.1 mm to about 25 mm.

[0055] The compact stacked assembly can include between 7-100 stacked conductive and insulating layers that form the mass analyzer, ionizer and detector.

[0056] The mass analyzer can be an ion trap that comprises a high density of through

apertures with centers of adjacent apertures spaced apart between about 1 μm to about 5000 μm.

[0057] The method can include providing an Einzel lens and placing the Einzel lens between the ionizer and the mass analyzer during the stacking of the integral assembly.

[0058] The detector planar conductor can be a thin conductive film on a substrate, and the providing the detector step can be carried out by orienting the thin conductive film to face an endcap electrode of the mass analyzer for the stacking.

[0059] The method can include providing at least one planar grid and placing the at least one planar grid between the ionizer and the mass analyzer and/or between the mass analyzer and the detector for the stacking step.

[0060] The detector at least one planar conductor can be a conductor on an integrated circuit amplifier.

[0061] The mass analyzer can include a CIT with concentric arrays of apertures, the method can include aligning the apertures before or during the stacking step.

[0062] The CIT can include at least one mesh endcap.

[0063] It is noted that aspects of the invention described with respect to one embodiment, may be incorporated in a different embodiment although not specifically described relative thereto. That is, all embodiments and/or features of any embodiment can be combined in any way and/or combination. Applicant reserves the right to change any originally filed claim and/or file any new claim accordingly, including the right to be able to amend any originally filed claim to depend from and/or incorporate any feature of any other claim or claims although not originally claimed in that manner. These and other objects and/or aspects of the present invention are explained in detail in the specification set forth below. Further features, advantages and details of the present invention will be appreciated by those of ordinary skill in the art from a reading of the figures and the detailed description of the preferred embodiments that follow, such description being merely illustrative of the present invention.

Brief Description of the Drawings

[0064] **Figure 1A** is an enlarged schematic illustration of a side view of an example of a compact, stacked assembly of planar components that provide an ion source, mass analyzer and detector according to embodiments of the present invention.

[0065] **Figure 1B** is an enlarged schematic illustration of a side view of another example of a compact, stacked assembly of planar components that provide an ion source,

mass analyzer and detector according to embodiments of the present invention.

[0066] **Figure 2A** is a schematic illustration of a side view of an ion trap array shown in **Figures 1A** and **1B**.

[0067] **Figure 2B** is a top view of an example of a ring electrode of the ion trap array shown in **Figure 2A** according to embodiments of the present invention.

[0068] **Figure 2C** is a top view of an example of an endcap electrode for the ion trap array shown in **Figure 2A** according to embodiments of the present invention.

[0069] **Figure 3A** is a schematic illustration of a side view of the ion source shown in **Figure 1A** and **1B**.

[0070] **Figure 3B** is a top view of the device shown in **Figure 3A** according to embodiments of the present invention.

[0071] **Figure 4A** is a schematic illustration of a side view of an exemplary detector suitable for the stacked assembly shown in **Figure 1A** and **1B**.

[0072] **Figure 4B** is a top view of the detector shown in **Figure 4A** according to embodiments of the present invention.

[0073] **Figure 5A** is a schematic illustration of a side view of another exemplary detector suitable for the stacked assembly shown in **Figure 1A** and **1B**.

[0074] **Figure 5B** is a top view of the detector shown in **Figure 5A** according to embodiments of the present invention.

[0075] **Figure 6A** is a schematic illustration of another stacked assembly according to embodiments of the present invention.

[0076] **Figure 6B** is a schematic illustration of another stacked assembly according to embodiments of the present invention.

[0077] **Figure 7** is a schematic illustration of another stacked assembly according to embodiments of the present invention.

[0078] **Figure 8A** is a schematic illustration of an exemplary side view of a lens array shown in **Figure 7** according to embodiments of the present invention.

[0079] **Figure 8B** is a top view of the conductive electrodes of the lens shown in **Figure 8A** according to embodiments of the present invention.

[0080] **Figure 9** is schematic illustration of a mass spectrometry system with a stacked assembly of MS components (ion source, analyzer and detector) according to embodiments of the present invention.

[0081] **Figure 10** is a block diagram of a mass spectrometry system according to embodiments of the present invention.

[0082] **Figure 11** is an exemplary timing diagram of a mass spectrometry system according to some embodiments of the present invention.

[0083] **Figure 12** is a flow chart of operations that can be used to fabricate an assembly for a mass spectrometry system according to embodiments of the present invention.

Description of Embodiments of the Invention

[0084] The present invention will now be described more fully hereinafter with reference to the accompanying figures, in which embodiments of the invention are shown. This invention may, however, be embodied in many different forms and should not be construed as limited to the embodiments set forth herein. Like numbers refer to like elements throughout. In the figures, certain layers, components or features may be exaggerated for clarity, and broken lines illustrate optional features or operations unless specified otherwise. In addition, the sequence of operations (or steps) is not limited to the order presented in the figures and/or claims unless specifically indicated otherwise. In the drawings, the thickness of lines, layers, features, components and/or regions may be exaggerated for clarity and broken lines illustrate optional features or operations, unless specified otherwise.

[0085] The terminology used herein is for the purpose of describing particular embodiments only and is not intended to be limiting of the invention. As used herein, the singular forms, "a", "an" and "the" are intended to include the plural forms as well, unless the context clearly indicates otherwise. It will be further understood that the terms "comprises," "comprising," "includes," and/or "including" when used in this specification, specify the presence of stated features, regions, steps, operations, elements, and/or components, but do not preclude the presence or addition of one or more other features, regions, steps, operations, elements, components, and/or groups thereof. As used herein, the term "and/or" includes any and all combinations of one or more of the associated listed items. As used herein, phrases such as "between X and Y" and "between about X and Y" should be interpreted to include X and Y. As used herein, phrases such as "between about X and Y" mean "between about X and about Y." As used herein, phrases such as "from about X to Y" mean "from about X to about Y."

[0086] It will be understood that when a feature, such as a layer, region or substrate, is referred to as being "on" another feature or element, it can be directly on the other feature or element or intervening features and/or elements may also be present. In contrast, when an element is referred to as being "directly on" another feature or element, there are no intervening elements present. It will also be understood that, when a feature or element is

referred to as being "connected", "attached" or "coupled" to another feature or element, it can be directly connected, attached or coupled to the other element or intervening elements may be present. In contrast, when a feature or element is referred to as being "directly connected", "directly attached" or "directly coupled" to another element, there are no intervening elements present. Although described or shown with respect to one embodiment, the features so described or shown can apply to other embodiments.

[0087] Unless otherwise defined, all terms (including technical and scientific terms) used herein have the same meaning as commonly understood by one of ordinary skill in the art to which this invention belongs. It will be further understood that terms, such as those defined in commonly used dictionaries, should be interpreted as having a meaning that is consistent with their meaning in the context of the present application and relevant art and should not be interpreted in an idealized or overly formal sense unless expressly so defined herein. Well-known functions or constructions may not be described in detail for brevity and/or clarity.

[0088] Spatially relative terms, such as "under", "below", "lower", "over", "upper" and the like, may be used herein for ease of description to describe one element or feature's relationship to another element(s) or feature(s) as illustrated in the figures. It will be understood that the spatially relative terms are intended to encompass different orientations of the device in use or operation in addition to the orientation depicted in the figures. For example, if the device in the figures is inverted, elements described as "under" or "beneath" other elements or features would then be oriented "over" the other elements or features. Thus, the exemplary term "under" can encompass both an orientation of over and under. The device may be otherwise oriented (rotated 90 degrees or at other orientations) and the spatially relative descriptors used herein interpreted accordingly. Similarly, the terms "upwardly", "downwardly", "vertical", "horizontal" and the like are used herein for the purpose of explanation only unless specifically indicated otherwise.

[0089] It will be understood that, although the terms first, second, etc. may be used herein to describe various elements, components, regions, layers and/or sections, these elements, components, regions, layers and/or sections should not be limited by these terms. These terms are only used to distinguish one element, component, region, layer or section from another region, layer or section. Thus, a first element, component, region, layer or section discussed below could be termed a second element, component, region, layer or section without departing from the teachings of the present invention.

[0090] The term "about" means that the stated number can vary from that value by +/-

10%.

[0091] The term "analyte" refers to a molecule or chemical(s) in a sample undergoing analysis. The analyte can comprise chemicals associated with any industrial products, processes or environments or environmental hazards, toxins such as toxic industrial chemicals or toxic industrial materials, and the like. Moreover, analytes can include biomolecules found in living systems or manufactured such as biopharmaceuticals.

[0092] The term "mass resonance scan time" refers to mass selective ejection of ions from the ion trap with associated integral signal acquisition time.

[0093] Embodiments of the invention are directed to compact configurations/packaging of the fundamental components of a device that determines ion mass to charge ratio and can additionally provide relative abundance information for a number of ions ranging across mass to charge values. The specific examples described herein are particularly relevant to ion trap mass analyzers but may be relevant to other types of mass analyzers. Generally, stated, the arrangement of the ionizer components and/or detector components with respect to the mass analyzer components allows significant reductions in size and weight over current designs.

[0094] Referring now to the figures, **Figure 1A** shows a compact mass spectrometer assembly **10** that includes the ionization source **30**, a mass analyzer **20** (such as, but not limited to, an ion trap mass analyzer), and the detector **40**, all arranged as a releasably attached set or integrally attached unit of stacked planar conductor and insulator components, e.g., typically alternating conductive and insulating films, substrates, sheets, plates and/or layers or combinations thereof, with defined features for the desired function.

[0095] The assembly **10** can have a compact planar shape, typically having a perimeter that bounds an area that is between about 0.01 mm^2 to about 25cm^2, including between about 0.01 mm^2 and 10 cm^2 and including between about 0.1 mm^2 and about 10 mm^2. For stack assemblies having polygonal perimeter shapes, the sides can be between about 0.1 mm to 10 cm, which may be in width and length dimensions "W" and "L". In some embodiments, each perimeter side (e.g., W and L) can be between about 0.1 mm to about 5 cm.

[0096] The thickness "t" can be between about 0.01 mm to about 25 mm, including between 0. 1 mm and 25 mm, between 0.25 mm and 25 mm, and between 0.1 mm and 1 mm. The thickness "t" can be about 0.1 mm, about 0.2 mm, about 0. 3mm, about 0.4 mm, about 0.5 mm, about 0. 6 mm, about 0. 7 mm, about 0.8 mm, about 0. 9mm, about 10 mm, about 11 mm, about 12 mm, about 13 mm, about 14 mm, about 15 mm, about 16 mm, about 17 mm,

about 18 mm, about 19 mm, about 20 mm, about 21 mm, about 22 mm, about 23 mm, about 24 mm, and about 25 mm.

[0097] The different components and/or alternating conductors and insulators can be clamped together, brazed, adhesively attached, formed as stacked substrates, or bonded or otherwise attached or formed to have the proper alignment of the apertures and other features (e.g., lens, detector surface, etc...).

[0098] The mass analyzer **20** can be configured in layers forming CITs, rectilinear ion traps, linear quadrupoles, Wien filters, or any other type of mass analyzer that could be implemented with patterned planar conducting and insulating layers.

[0099] **Figure 1B** shows an assembly **10** similar to that shown in **Figure 1A**, but with the inclusion of two planar conductive grids **60**, **62**. One grid **60** can be placed intermediate the electrode **23** and the detector **40** and the other, where used, can be placed intermediate the electrode **22** and the ion source (e.g., electrode **31**). An insulator **141**, **131** can reside between the respective grid **60**, **62** and the corresponding respective electrode **23**, **22**. The assembly **10** can omit one or both of these grids **60**, **62**. As is known to those of skill in the art, a "grid" refers to a conductive planar sheet with a pattern of apertures or open windows, in a defined geometric shape, typically the grid apertures have a constant size and shape (which can be smaller or larger than the ion sources and the end cap apertures but typically smaller). The grid **60**, **62** can be biased to turn the conduction of charged particles on or off by appropriately controlling the electric potentials of the grids relative to their adjacent electrodes. The device could be operated with either grid **60**, **62** or with both grids (or no grids). The grid can be rectangular and extend across a width and length dimension substantially commensurate with the array of electrodes **21, 22, 23**. The grids **60**, **61** can have a smaller thickness than the respective adjacent electrode **23**, **22** and/or **31**.

[00100] As will be discussed further below, as shown in **Figure 7**, the planar stacked assembly **10** can include additional components, such as a planar lens **50**, all in the same compact package or foot print dimensions noted.

[00101] Examples of conductors for the various conductive components, e.g., the CIT electrodes **21**, **22**, **23**, the detector electrode(s) **41** (**Figures 4A, 5A**), the ionizer electrodes **31**, **32** and lens conductors **51**, **52**, **53** (where used) include, but are not limited to, one or more of metals such as brass, stainless steel, copper, Beryllium copper, gold, plated or coated metals or substrates such as stainless steel with one-sided gold plating (Au/SS), doped semiconductors, typically n or p heavily doped silicon (Si), germanium (Ge) or Arsenic-doped germanium semiconductor (GaAs). The conductors can be a solid (e.g., continuous

surface) conductor or a mesh conductor or thin films of conductive material on a substrate. The term "thin film" refers to coatings that have a thickness of between about 1 nm to about 10 μm.

[00102] Examples of insulators for the various insulator components, e.g., the CIT insulators **120**, **121**, the detector insulators **140**, **142**, the ionizer insulators **130**, **133** and the lens insulators **54**, **150** (where used) include, but are not limited to, one or more of Teflon®, mylar, mica, insulating ceramics, polyimide, macor, kapton, SiO_2, Si_3N_4 and ambient gas surrounding the electrode stack **10** in a chamber, said chamber could possibly be at reduced pressures compared to ambient. The term "insulator" refers to an electrical insulator and can comprise a solid substrate, a mesh substrate, a patterned substrate with spatial elements removed, a thin film coating of a suitable material on a conductor surface or a gas.

[00103] In some embodiments, all of the alternating planar insulator and conductive layers are stacked so that adjacent conductive and insulating layers are in intimate, abutting contact. The stacked insulating and conductive layers can be provided in any suitable numbers to provide the source, mass analyzer and detector components, typically between about 7-100 layers, and more typically between 15 and 50 layers. In some embodiments, the cumulative number of insulator and conductor layers in a stack can be 9, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 42, 43, 44, 45, 46, 47, 48, 49 and 50, or about 50, about 60, about 70, about 80, about 90 and about 100 layers. A plurality of, a majority of, or even all the layers can be provided on one or more semiconductor substrates as an integrated circuit.

[00104] As shown in **Figures 1A**, **1B**, **2A**, **2B** and **2C**, the ion trap mass analyzer **20** can be a cylindrical ion trap (CIT) array **20a**. The CIT array **20a** includes three closely spaced apart electrodes (conductors) as is well known. The three electrodes include a center ring electrode **21** residing between two endcap electrodes **22**, **23**. The term "array" refers to cooperating planar components of the assembly**10a.** The term "aperture array", when used with CIT, for example, means that the CIT electrodes (or other component electrode/planar conductor) have axially aligned apertures with a distance between centers of adjacent apertures having a distance "**b**". The apertures can be arranged in a regular pattern or random. The ring electrode apertures **21a** will generally be larger than the first or second endcap electrode apertures **22a**, **23a**. The term "ring electrode" refers to the center electrode in the ion trap array that is between the endcap or end electrodes **22**, **23** and is not required to have a ring shape form factor, e.g., either in an outer perimeter or in a bounding channel of a respective ion trap. As is well known, a respective ion trap has a tubular channel of different

diameters of aligned endcap and ring apertures.

[00105] As shown in **Figures 2A and 2B**, the ring electrode **21** has a plurality of closely spaced through-apertures **21a**. The neighboring insulators **120**, **121** can have apertures that are aligned with and are substantially the same size or larger than those of the ring electrode **21** or may have apertures that reside just around or proximate the outer perimeter of member **21**, outside the array of apertures **21a**. The apertures **21a** each have a radius $\mathbf{r_0}$ or average effective radius (e.g., the latter calculates an average hole size using shape and width/height dimensions where non-circular aperture shapes are used) and a corresponding diameter or average cross distance $\mathbf{2r_0}$. In some embodiments, the array **20a** has an effective length $\mathbf{2z_0}$ measured as the distance between interior surfaces of endcaps. The array **20a** can be configured to have a defined ratio of z_0/r_0 that is near unity but is generally greater than unity by a few tens of percent. The r_0 and z_0 dimensions can be between about 0.5 μm to about 1 cm but for microscale mass spectrometry applications contemplated by preferred embodiments of the invention, these dimensions are preferably 1 mm or less, down to about 0.5μm.

[00106] Each aperture **21a** can be axially aligned with a corresponding aperture **22a**, **23a** of each of the adjacent end cap electrodes **22**, **23** (and insulators **120**, **121** where similar configurations of apertures are used) so that centers of each aperture **21a**, **22a**, **23a**, even with different size apertures, are aligned.

[00107] There can be a corresponding number of apertures **21a**, **22a**, **23a** on each of the ring **21** and endcap electrodes **22**, **23**. Endcap electrodes **22**, **23** typically have through holes or apertures **22a**, **23a** in them that are located axially symmetric about the ring electrode hole or holes **21a** with a diameter or average effective radius (e.g., (width + height)/2) that is smaller than that of the ring electrode apertures, such as between about 10-40%, typically between about 10-30%, and more typically between about 20-30% of the diameter or width of the respective aperture **21a** of the ring electrode **21**. In alternative embodiments, the endcap apertures, **22a** and **23a** can have diameters similar to, or larger than the ring aperture **21a**. In the case of these latter endcap aperture dimensions the apertures would typically be covered by a conductive mesh that is in electrical contact with the endcap electrode. The aperture array **20a** can be in any pattern and the apertures **22a**, **23a** can have any suitable shape as long as the ring to end endcap holes **21a** to **22a** and **21a** to **23a** are substantially (predominantly) axially aligned and symmetric. Different electrodes **21**, **22**, **23**, can have different aperture geometry, but preferably similar geometries excepting in cases where mesh is used with endcap electrodes.

[00108] The aperture array **20a** can be provided in a relatively high-density pattern of apertures. As shown in **Figures 2B** and **2C**, the array of apertures can be formed so that outer apertures define a perimeter shape **21p** that is substantially hexagonal with apertures in a closely-arranged pattern. This arrangement is an efficient use of electrode area. The center-to-center spacing, b, of the apertures must be greater than $2r_0$. In some embodiments, the distance "b" between neighboring apertures **21a**, **22a**, **23a** on respective electrodes can be 10% larger than $2r_0$ and in other embodiments b may be 50-100% larger than $2r_0$. A corresponding number of apertures can be provided in the electrodes and solid or mesh insulator of the ionizer array **30** and conductor components of the lens **50**, where used. The lens **50** can have apertures that are typically 1-1 with the ion trap and the ionizer features can be smaller than trap dimensions so there could be a plurality of ionizer features per ion trap.

[00109] As shown in **Figure 2A**, the endcap electrodes **22**, **23** are spaced a distance **d** away from the ring electrode **21**, typically in symmetric spacings. The specific spacing depends on the ring electrode thickness, but a distance spacing of the endcap electrodes **22**, **23** can be chosen to optimize mass spectrometry performance. This distance is typically chosen such that z_0 is slightly larger than r_0, typically 10-30% larger. Electrical insulators **120**, **121** with corresponding apertures separate the electrodes **21**, **22**, **23**. A respective insulator **120**, **121** can comprise a gas, a solid material, or a combination of the two. In some particular embodiments, the insulators **120**, **121** are one or more sheets of insulating substrate material with material removed so as to not interfere with the ring electrode apertures. The endcap apertures or holes **22a**, **23a** allow the injection of ionization energy or ions and the ejection of ions for detection purposes. Typically one end electrode would be used for injection of ions or ionizing energy (through one end electrode **22**) and the other end for ejection of ions (through the other end electrode **23**).

[00110] In some embodiments, the ring electrode **21** can be between about 500 μm to about 790 μm thick and the endcap electrodes **22**, **23** can be the same or less thick than the ring electrode, typically thinner, such as between about 10-50% the thickness of the ring electrode, e.g., about 250 μm thick. The spacing between electrodes can be set with polyimide washers (McMaster-Carr) to create a CIT **20** with desired critical dimensions, e.g., r_0 = 500 μm, z_0 = 645 μm. For further discussion of CIT configurations, *see* U.S. 6,933,498, and U.S. 6,469,298, the contents of which are hereby incorporated by reference as if recited in full herein. The ionizer **30** includes one or more planar conductors (e.g., electrode **31** and/or **32**). An example of a single electrode ionizer is described in Kornienko, Anal. Chem. 2000, 72, 559-562, the contents of which are hereby incorporated by reference as if recited in

full herein.

[00111] As shown in **Figures 3A** and **3B**, an exemplary ionizer (or ion source) **30** can comprise an ionizer array **30a** that includes closely spaced electrodes **31**, **32**, separated by an intermediately positioned insulator **133**. The insulator **133** can comprise an electrically insulating or non-conductive substrate or material layer or layers and/or a gap space (if the latter, the gap space can be filled by air or a buffer gas, typically at mass spectrometer vacuum, in operation). The term "ionizer array electrodes" indicates that the electrodes **31**, **32** provide a plurality of spaced apart sources **31s**, **32s** aligned with and symmetrically arranged with the array of ion traps.

[00112] The ionization source **30** for an array of ion traps **20a** can be a planar array of areas or zones that can lead to the production of ions for each of the CITs in the CIT array. **Figures 3A** and **3B** shows an exemplary design of an array ion source **30** where each light circular feature represents an ion source or sources **31s**, **32s**. Within each ion source **31s**, **32s**, there may be contained therein a plurality of apertures with lateral dimensions that can range from 10 μm down to about 1 μm, that act as sources of ions or electrons. The array of ionizers can have the same spatial pitch as the CIT array **20a**. Examples of types of ionization that can be provided in array form include, but are not limited to, cold field electron emitters, miniature gas plasma sources, and field ionization. In particular embodiments, as shown in **Figure 3A**, the ionization source **30** comprises two planar conductors **31**, **32** spaced apart by an insulator **33**. An array of micron-scale holes can be formed within the insulator **133** corresponding to the indicated ionization regions **31s**, **32s**. Applying an appropriate magnitude electrical potential between the two conducting electrodes **31**, **32** can generate electric field strengths to affect cold field emission of electrons, formation of a gas plasma, or field ionization of molecules or atoms. The close spatial proximity of the ionization array to the mass analyzer, such as the CIT described, is particularly advantageous for small mass spectrometry systems operating at high pressure (approximately > 1 Torr) due to the reduced mean free paths experienced by the ions or electrons at such pressures.

[00113] It is well known that CITs **20** generate mass spectral information by ejecting an ensemble of trapped ions in an orderly fashion such that ions of a given mass to charge range are ejected through the endcap holes **23a** during a defined or selected time period. Thus, the detector **40** comprises an appropriate transducer. The transducer typically comprises an electron multiplier but may be a planar detector **40** as shown in **Figures 1A**, **1B**, **4A** and **5A**. In particular embodiments, as shown in **Figures 4A** and **4B**, the detector **40**

comprises a Faraday cup configuration. However, other planar detectors may be used.

[00114] Referring to **Figures 4A** and **5A**, in some embodiments, the detector **40** may comprise a thin conductive film **40f** on an insulating substrate **42**. **Figures 4A** and **4B** illustrate an example of a planar detector **40** that has either a single charge sensitive site that collects ions from all traps from the CIT array **20a**. **Figures 5A** and **5B** illustrate an example of a planar detector **40** with an array **41a** of charge collection sites **41s** that can be used as a Faraday cup detector **41F**. The planar conductive detector **40** can comprise a thin conductive film **40f** on in contact with a non-conductive or insulating thin film or substrate **42**. The non-conductive film could be a thin layer of silicon dioxide or silicon nitride supported by a silicon wafer. Moreover, the substrate can be a semiconductor substrate such as a silicon wafer that could contain the electrical amplifying circuitry for amplifying the collected charge into a signal that could be measured by an analog to digital conversion chip connected to an electrical controller and signal processor.

[00115] Charge detection provided by the planar detector **40** may be particularly attractive for small mass spectrometry systems due to their inherently small size and weight and the ability to operate at pressures from low vacuum to atmospheric pressure. Charges collected by the conductive film **40f** or other conductor associated with the detector **40** can be measured either with an electrometer or a charge sensitive transimpedance amplifier. The term "electronic collector" refers to an electronic circuit that can detect charges collected by the film and/or conductor.

[00116] For example, the detector **40** can be configured to detect ions ejected in parallel from a planar CIT array with a planar electrode with a solid continuous conductive surface **41c** over the holes of the endcap electrode **23a** as shown in **Figures 4A** and **4B**. The gain of a charge sensitive transimpedance amplifier may be improved with reduced Faraday cup capacitance. Thus, a Faraday cup conductor **41F** can be used. The Faraday cup **41F** can be configured as an array of conductive Faraday cups **41a** with geometrically shaped collection sites **41s** as shown in **Figure 5A** and **5B** which in some embodiments may be preferable. The array of Faraday cups **41a** can have a single electrical trace or connection **45** to an amplifier so as to be connected in parallel as shown in **Figure 5B** or they can be addressed separately by separate electronic amplifiers (with separate electrical traces or connections) or by a single amplifier through a multiplexer. An insulating material **42** and/or gap space can reside between the endcap electrode **23** and the detector **40**.

[00117] The close spatial proximity of the detector to the mass analyzer, such as the CIT described, is particularly advantageous for small mass spectrometry systems operating at

high pressure (approximately > 1 Torr) due to the reduced mean free paths experienced by the ejected ions at such pressures.

[00118] **Figure 6A** illustrates another embodiment of the compact assembly **10'**. In this embodiment, the ionizer array **30** shares an electrode with the CIT array **20a**. That is, the endcap electrode **22** can also be used as the adjacent ionizer array electrode (eliminating the need for electrode **31** shown in **Figure 1**) or the ionizer electrode **31** can also used as the endcap electrode **23**. Thus, this assembly **10'** illustrates a stacked assembly of conductors and insulators where one of the CIT endcap electrodes **23** is formed by one of the ionizer conducting electrodes **31** to reduce the complexity and overall size of the mass spectrometry assembly.

[00119] As shown in **Figure 6B**, in some embodiments, the assembly **10a** can be configured so that one or more of the at least one ionizer electrode **31** or **32** can be switched electrically and also used as the detector electrode **40**, e.g., a collector electrode for the Faraday cup **41F**.

[00120] As shown in **Figure 7**, another element that can be used in the transport of charged particles is an Einzel lens **50**. An Einzel lens **50** includes three planar annular electrodes **51**, **52**, **53** equally spaced about where different electric potentials are applied to the separate electrodes of the ionizer **30** so as to focus the charged particles. Insulating gaps of air/gas or solid/insulating substrate material **54** can reside between the intermediate electrode **52** and each adjacent annular end electrode **51**, **53**. In the case of a solid insulating substrate **54**, some of the substrate material can be removed or formed so as to allow clear aperture spaces aligned with and through the one or more lens apertures **50a**. An array of Einzel lens apertures **50a** can be formed as shown in **Figure 8** where all of the lenses could have the same focal distance if they are all the same size. The Einzel lens array **50a** resides between the ionizer **30** and the ion trap **20**. Each lens **50a** can have substantially the same size as corresponding apertures **21a** of the ring electrode. The design of Einzel lenses is well known to those trained in the art of ion optics.

[00121] The features in the different conductors and insulators can be provided using any suitable method, including, but not limited to, one or more of conventional machining, drilling, milling, and CNC milling, ultrasonic milling, electrical discharge machining, deep reactive ion etching, wet chemical etching, water jet machining, laser water jet machining and laser machining. Resolution in a CIT array can be limited by the precision of the fabrication technique utilized. Variations in hole diameter, placement and alignment between electrodes **21**, **22**, **23** can cause small differences between individual traps resulting in decreased

resolution for the array **20a**. Thus, precision fabrication may be preferred so that tolerances are within a high degree of accuracy. A MEMS fabrication process such as bulk micromachining or surface micromachining can be used where semiconductor materials are used to form the conductor and/or insulator components.

[00122] **Figure 9** illustrates a portable MS system **100** with a housing **100h** that encloses the assembly **10**, typically inside a chamber **105**, which may comprise at least one vacuum chamber (the chamber is shown by the broken line around the stacked assembly **10**).

[00123] In some embodiments, the housing **100h** can releasably attach a canister **110** of pressurized buffer gas "B" that connects to a flow path into the (vacuum) chamber **105**. The housing **100h** can hold a control circuit **200** and various power supplies **205**, **210**, **215**, **220** that connect to conductors to carry out the ionization, mass analysis and detection. The housing **100h** can hold one or more amplifiers including an output amplifier **250** that connects to a processor **255** for generating the mass spectra output.

[00124] The portable system **100** can be lightweight, typically between about 1-15 pounds (not including a vacuum pump, where used), inclusive of the buffer gas supply **110**, where used. The housing **100h** can be configured as a handheld housing, such as having a form factor similar in size and weight as a Microsoft® Xbox®, Sony® PLAYSTATION® or Nintendo® Wii® game console or game controller, or similar to a form factor associated with an electronic notebook, PDA, IPAD or smartphone and may optionally have a pistol grip **100g** that holds the control circuit **200**. However, other configurations of the housing may be used as well as other arrangements of the control circuit. The housing **100h** typically holds a display screen and can have a User Interface such as a Graphic User Interface.

[00125] The system **100** may also include a transceiver, GPS module and antenna and can be configured to communicate with a smartphone or other pervasive computing device (laptop, electronic notebook, PDA, IPAD, and the like) to transfer data or for control of operation, e.g., with a secure APP or other wireless programmable communication protocol.

[00126] The system **100** can be configured to operate at pressures at or greater than about 100 mTorr up to atmospheric.

[00127] In some embodiments, the mass spectrometer **100** is configured so that the ion source (ionizer) **30**, mass analyzer **20** and detector **40** operate at near isobaric conditions and at a pressure that is greater than 100 mTorr. The term "near isobaric conditions" include those in which the pressure between any two adjacent chambers differs by no more than a factor of 100, but typically no more than a factor of 10.

[00128] As shown in **Figure 10**, the spectrometer **100** can include the stacked

assembly **10** and an arbitrary function generator **215g** to provide a low voltage axial RF input **215** to the ion trap **20** during mass scan for resonance ejection. The low voltage axial RF can be between about 100 mVpp to about 8000 mVpp, typically between 200 to 2000 mVpp. The axial RF **215s** can be applied to a CIT endcap **22** or **23**, typically end cap **23**, or between the two endcaps **22** and **23** during a mass scan for facilitating resonance ejection.

[00129] As shown in **Figures 9** and **10**, the device **100** includes an RF power source **205** that provides an input signal to the ring electrode **21**. The RF source **205** can include an RF signal generator, RF amplifier and RF power amplifier. Each of these components can be held on a circuit board in the housing **100h** enclosing the ion trap **20** in the vacuum chamber **105**. In some embodiments, an amplitude ramp waveform can be provided as an input to the RF signal generator to modulate the RF amplitude. The low voltage RF can be amplified by a RF preamplifier then a power amplifier to produce a desired RF signal. The RF signal can be between about 1 MHz to 1000 MHz depending on the size of the ring electrode features. As is well known to those trained in the art, the RF frequency depends reciprocally on the ring electrode radius, r_0. A typical RF frequency for an r_0 of 500 μm would be 5-20 MHz. The voltages can be between 100 V_{0p} to about 1500 V_{0p}, typically up to about 500 V_{0p}.

[00130] Generally stated, electrons are generated in a well-known manner by source **30** and are directed towards the mass analyzer (e.g., ion trap) **20** by an accelerating potential. Electrons ionize sample gas **S** in the mass analyzer **20**. For ion trap configurations, RF trapping and ejecting circuitry is coupled to the mass analyzer **20** to create alternating electric fields within ion trap **20** to first trap and then eject ions in a manner proportional to the mass to charge ratio of the ions. The ion detector **40** registers the number of ions emitted at different time intervals that correspond to particular ion masses to perform mass spectrometric chemical analysis. The ion trap dynamically traps ions from a measurement sample using a dynamic electric field generated by an RF drive signal **205s**. The ions are selectively ejected corresponding to their mass-charge ratio (mass (m)/charge (z)) by changing the characteristics of the radio frequency (RF) electric field (e.g., amplitude, frequency, etc.) that is trapping them. These ion numbers can be digitized for analysis and can be displayed as spectra on an onboard and/or remote processor **255**.

[00131] In the simplest form, a signal of constant RF frequency **205s** can be applied to the center electrode **21** relative to the two end cap electrodes **22, 23**. The amplitude of the center electrode signal **205s** can be ramped up linearly in order to selectively destabilize different m/z of ions held within the ion trap. This amplitude ejection configuration may not result in optimal performance or resolution. However, this amplitude ejection method may

be improved upon by applying a second signal **215s** differentially across the end caps **22, 23**. This axial RF signal **215s**, where used, causes a dipole axial excitation that can result in the resonant ejection of ions from the ion trap when the ions' secular frequency of oscillation within the trap matches the end cap excitation frequency.

[00132] The ion trap **20** or mass filter can have an equivalent circuit that appears as a nearly pure capacitance. The amplitude of the voltage **205s** to drive the ion trap **20** may be high (e.g., 100 V - 1500 Volts) and can employ a transformer coupling to generate the high voltage. The inductance of the transformer secondary and the capacitance of the ion trap can form a parallel tank circuit. Driving this circuit at resonant frequency may be desired to avoid unnecessary losses and/or an increase in circuit size.

[00133] The vacuum chamber **105** can be in fluid communication with at least one pump (not shown). The pumps can be any suitable pump such as a roughing pump and/or a turbo pump including one or both a TPS Bench compact pumping system or a TPS compact pumping system from Varian (now Agilent Technologies). The pump can be in fluid communication with the vacuum chamber **105**. In some embodiments, the vacuum chamber can have a high pressure during operation, e.g., a pressure greater than 100 mTorr up to atmospheric. High pressure operation allow elimination of high-vacuum pumps such as turbo molecular pumps, diffusion pumps or ion pumps. Operational pressures above approximately 100 mTorr can be easily achieved by mechanical displacement pumps such as rotary vane pumps, reciprocating piston pumps, or scroll pumps.

[00134] Sample **S** may be introduced into the vacuum chamber **105** with a buffer gas **B** through an input port toward the ion trap **20**. The **S** intake from the environment into the housing **100h** can be at any suitable location (shown by way of example only from the bottom). One or more Sample intake ports can be used.

[00135] The buffer gas **B** can be provided as a pressurized canister **110** of buffer gas as the source. However, any suitable buffer gas or buffer gas mixture including air, helium, hydrogen, or other gas can be used. Where air is used, it can be pulled from atmosphere and no pressurized canister or other source is required. Typically, the buffer gas comprises helium, typically above about 90% helium in suitable purity (e.g., 99% or above). A mass flow controller (MFC) can be used to control the flow of pressurized buffer gas **B** from pressurized buffer gas source **110** with the sample **S** into the chamber **105**. When using ambient air as the buffer gas, a controlled leak can be used to inject air buffer gas and environmental sample into the vacuum chamber. The controlled leak design would depend on the performance of the pump utilized and the operating pressure desired.

[00136] **Figure 11** illustrates an exemplary timing diagram that can be used to carry out/control various components of the mass spectrometer **100**. The drive RF amplitude signal can be driven using a ramp waveform that modulates the RF amplitude throughout the mass scan and the other three pulses control ionization, detection and axial RF voltages applied. As shown, initially, 0 V can optionally be applied to the gate lens **50** (where used) to allow electrons to pass through during the ionization period. Alternatively, this signal can be applied to the ionizer **30** directly to turn on and off the production of electrons or ions. The drive RF amplitude **205s** can be held at a fixed voltage during an ionization period to trap ions generated inside the CIT **20**. At the end of the ionization period, the gate lens voltage (if used) is driven to a potential to block the electron beam of the ionizer **30** and stop ionization. The drive RF amplitude **205s** can then be held constant for a defined time, e.g., about 5 ms, to allow trapped ions to collisionally cool towards the center of the trap. The drive RF amplitude **205s** can be linearly ramped to perform a mass instability scan and eject ions toward the detector **40** in order of increasing *m/z*. The axial RF signal **215s** can be synched to be applied with the start of ramp up of the RF amplitude signal linear ramp up (shown at t=6 ms, but other times may be used) so as to be substantially simultaneously gated on to perform resonance ejection during the mass scan for improved resolution and mass range. Data is acquired during the mass instability scan to produce a mass spectrum. Finally, the drive RF amplitude **205s** can be reduced to a low voltage to clear any remaining ions from the trap **20** and prepare it for the next scan. A number of ion manipulation strategies can be applied to ion trap devices such as CITs, as is well known to those trained in the art. All of the different strategies to eject, isolate, or collisionally dissociate ions can be applied to the ion trapping structures discussed in the application.

[00137] **Figure 12** is a flow chart of exemplary fabrication steps that can be used to assemble planar components to form a compact assembly for a mass spectrometry system. As shown, a mass analyzer can be provided as a plurality of closely stacked, spaced apart planar electrodes (block **300**). The mass analyzer can be preassembled or assembled with the assembly of the other components. A detector comprising at least one planar conductor can be provided (block **305**). The planar conductor can be provided as a silicon wafer that contains signal processing electronics. Optionally, the detector can include a planar insulator, but this is not required for embodiments including a separate electronic collector. An ionizer **30** can include one or more planar conductors (block **310**). Optionally, the ionizer can include more than one conductor such as a pair of conducting electrodes on opposing sides of an insulating spacer as described above. The mass analyzer, the detector and the ionizer can

be attached together to form a stacked integral assembly having a perimeter with each side having a size between 0.1 mm to about 10 cm, more typically between about 1 mm to 5 cm and a stack thickness of between about 0.1 mm to about 25 mm (block **315**).

[00138] The stacked assembly can comprise a high density of through apertures with centers of adjacent apertures spaced apart between about 1 μm to about 5000 μm (block **302**).

[00139] The centerlines of apertures in the ring electrode can be aligned with corresponding apertures in the endcap electrodes during or before the attaching step (block **311**).

[00140] The method can include providing an Einzel lens as a plurality of closely spaced apart annular electrodes (block **312**). The Einzel lens array can be placed between the ionizer and the mass analyzer, then attaching the components to define the stacked integral assembly (block **314**).

[00141] Embodiments described herein operate to reduce the power and size of a mass spectrometer so that the mass spectrometer system **10** may become a component in other systems that previously could not use such a unit because of cost and the size of conventional units.

[00142] One or more mass spectrometers **10** may be placed in or at a hazard site to analyze gases and remotely send back a report of conditions presenting danger to personnel. A mass spectrometer **10** may be placed at strategic positions on air or land transport to test the environment for hazardous gases that may be an indication of malfunction or even a terrorist threat. Embodiments of the present invention provide mass spectrometers suitable for handheld, field use.

[00143] Embodiments of the present invention may take the form of software and hardware aspects, all generally referred to herein as a "circuit" or "module." The processor can include one or more digital microprocessors.

[00144] As will be appreciated by one of skill in the art, features or embodiments of the present invention may be embodied as an apparatus, a method, data or signal processing system, or computer program product. Furthermore, certain embodiments of the present invention may include an Application Specific Integrated Circuit (ASIC) and/or computer program product on a computer-usable storage medium having computer-usable program code means embodied in the medium. Any suitable computer readable medium may be utilized including hard disks, CD-ROMs, optical storage devices, or magnetic storage devices.

[00145] The computer-usable or computer-readable medium may be, but is not limited

to, an electronic, magnetic, optical, electromagnetic, infrared, or semiconductor system, apparatus, device, or propagation medium. More specific examples (a non-exhaustive list) of the computer-readable medium would include the following: an electrical connection having one or more wires, a portable computer diskette, a random access memory (RAM), a read-only memory (ROM), an erasable programmable read-only memory (EPROM or Flash memory), an optical fiber, and a portable compact disc read-only memory (CD-ROM). Note that the computer-usable or computer-readable medium could even be paper or another suitable medium, upon which the program is printed, as the program can be electronically captured, via, for instance, optical scanning of the paper or other medium, then compiled, interpreted or otherwise processed in a suitable manner if necessary, and then stored in a computer memory.

[00146] Computer program code for carrying out operations of the present invention may be written in an object oriented programming language such as Java7, Smalltalk, Python, Labview, C++, or VisualBasic. However, the computer program code for carrying out operations of the present invention may also be written in conventional procedural programming languages, such as the "C" programming language or even assembly language. The program code may execute entirely on the spectrometer computer and/or processor, partly on the spectrometer computer and/or processor, as a stand-alone software package, partly on the spectrometer computer and/or processor and partly on a remote computer, processor or server or entirely on the remote computer, processor and/or server. In the latter scenario, the remote computer, processor and/or server may be connected to the spectrometer computer and/or processor through a LAN or a WAN, or the connection may be made to an external computer, processor and/or server (for example, through the Internet using an Internet Service Provider).

[00147] The flowcharts and block diagrams of certain of the figures herein illustrate the architecture, functionality, and operation of possible implementations of mass spectrometers or assemblies thereof and/or programs according to the present invention. In this regard, each block in the flow charts or block diagrams represents a module, segment, operation, or portion of code, which comprises one or more executable instructions for implementing the specified logical function(s). It should also be noted that in some alternative implementations, the functions noted in the blocks might occur out of the order noted in the figures. For example, two blocks shown in succession may in fact be executed substantially concurrently or the blocks may sometimes be executed in the reverse order, depending upon the functionality involved.

[00148] The foregoing is illustrative of the present invention and is not to be construed as limiting thereof. Although a few exemplary embodiments of this invention have been described, those skilled in the art will readily appreciate that many modifications are possible in the exemplary embodiments without materially departing from the novel teachings and advantages of this invention. Accordingly, all such modifications are intended to be included within the scope of this invention as defined in the claims. The invention is defined by the following claims, with equivalents of the claims to be included therein.

THAT WHICH IS CLAIMED:

1. An assembly for a mass spectrometry system, comprising:

an ionizer comprising at least one planar conductor;

a mass analyzer comprising a planar electrode assembly; and

a detector comprising at least one planar conductor,

wherein the ionizer, the mass analyzer and the detector are attached together in a compact planar stacked assembly, and wherein the stacked assembly has a perimeter that bounds an area that is between about 0.01 mm^2 to about 25 cm^2 and has a thickness that is between about 0.1 mm to about 25 mm.

2. The assembly of Claim 1, wherein the ionizer, detector and mass analyzer are configured as respective cooperating ionizer arrays, detector arrays and mass analyzer arrays.

3. The assembly of Claim 1 or 2, wherein the detector at least one planar electrode comprises a Faraday cup electrode.

4. The assembly of Claim 3, wherein the Faraday cup electrode comprises a thin conductive film on a substrate.

5. The assembly of Claim 3, wherein the ionizer planar conductor is configured to cooperate with the detector to define a collection electrode for the Faraday cup.

6. The assembly of Claim 3, wherein the Faraday cup electrode comprises a conductive layer with a substantially continuous conductive surface.

7. The assembly of Claim 3, wherein the mass analyzer comprises an ion trap, wherein the Faraday cup electrode comprises a conductive layer in a shaped pattern of conductive regions that overlie and align with corresponding apertures in an adjacent electrode of the ion trap.

8. The assembly of Claim 4, wherein the substrate is a semiconductor forming an integrated circuit.

9. The assembly of Claim 7, wherein the conductive layer comprises a single trace or

strip that connects each conductive region to an electronic collector.

10. The assembly of any of Claims 1-9, wherein the ionizer comprises a pair of planar conductors that define array electrodes separated by an insulator.

11. The assembly of any of Claims 1-9, wherein the mass analyzer comprises an ion trap array, and wherein a first endcap electrode of the ion trap array defines one of the at least one planar electrode of the ionizer.

12. The assembly of any of Claims 1-9, further comprising an Einzel lens comprising a plurality of spaced apart electrodes residing between the ionizer and the mass analyzer.

13. The assembly of Claim 12, wherein the mass analyzer is a cylindrical ion trap, wherein the Einzel lens electrodes comprise an array of lens apertures that align with corresponding apertures of the ion trap, wherein the Einzel lens apertures have a size that substantially correspond to an aperture size of the ring electrode.

14. The assembly of any of Claims 1-13, further comprising at least one planar grid that resides between either (i) the mass analyzer and the detector or (ii) the mass analyzer and the ionizer.

15. The assembly of any of Claims 1-14, further comprising first and second planar grids, the first grid residing between the mass analyzer and the detector and the second grid residing between the mass analyzer and the ionizer.

16. The assembly of any of Claims 1-15, wherein the stacked assembly comprises between 7-100 stacked conductive and insulating layers that form the mass analyzer, ionizer and detector.

17. The assembly of any of Claims 1-15, wherein the mass analyzer comprises a planar ring electrode and first and second opposing planar endcap electrodes, wherein the ion trap has an aperture array of at least 10 spaced apart apertures with centers of adjacent apertures residing between about 1 μm to about 5000 μm apart.

18. The assembly of any of Claims 1-17, wherein the detector at least one planar conductor includes a conductor on an integrated circuit amplifier.

19. The assembly of any of Claims 1-18, wherein the mass analyzer comprises a CIT with concentric arrays of apertures.

20. The assembly of any of Claims 1-19, wherein the mass analyzer comprises at least one mesh endcap.

21. The assembly of any of Claims 1-20, wherein the detector at least one planar conductor comprises at least one of the following:

a single conductor, a single conductor on an insulator, an array of conductors that are connected or addressable by an amplifier.

22. A portable high-pressure mass spectrometer, comprising:

a housing;

a chamber inside the housing;

a compact stacked assembly held inside the chamber, the compact stacked assembly comprising:

an ionizer comprising at least one planar conductor;

a mass analyzer comprising a planar electrode assembly; and

a detector comprising at least one planar conductor,

a drive RF power source in the housing in communication with the mass analyzer; and

a control circuit held by the housing configured to control activation and/or deactivation of the ionizer, the drive RF power source, and the detector,

wherein the compact stack assembly has a perimeter that bounds an area that is between about 0.1 mm^2 to about 25 cm^2 and has a thickness that is between about 0.1 mm to about 25 mm.

23. The mass spectrometer of Claim 22, wherein the mass analyzer is an ion trap that comprises a planar ring electrode and first and second opposing planar endcap electrodes, wherein the ion trap has an aperture array of at least 10 spaced apart apertures with centers of adjacent apertures residing between about 1 μm to about 5000 μm apart.

24. The mass spectrometer of Claim 22 or 23, further comprising an axial RF power source held inside the housing and electrically connected to the mass analyzer, wherein the control circuit is configured to control operation of the axial RF power source.

25. The mass spectrometer of any of Claims 22-24, further comprising a pressurized buffer gas source in fluid communication with the housing for providing a buffer gas to the chamber.

26. The mass spectrometer of any of Claims 22-25,wherein the housing is configured to controllably receive ambient air as buffer gas in the chamber.

27. The mass spectrometer of any of Claims 22-26, wherein the spectrometer is configured to be a hand-held, light weight spectrometer having a weight between about 1-15 pounds, exclusive of a vacuum pump, and wherein the mass spectrometer chamber is a vacuum chamber that is configured to operate at high pressure of about 100 mTorr or greater.

28. The mass spectrometer of any of Claims 23-27, wherein the housing is sized and configured as a handheld housing with a display providing a user interface (UI) or in communication with a UI.

29. The mass spectrometer of Claim 24, wherein the axial RF power source is configured to apply a low voltage axial RF input signal to an endcap electrode or between the two endcap electrodes of the mass analyzer during a mass scan.

30. The mass spectrometer of any of Claims 22-29, wherein the planar conductor of the detector is configured as a Faraday cup electrode that comprises a conductive layer on a semiconductor substrate with a substantially continuous conductive surface.

31. The mass spectrometer of any of Claims 22-29, wherein the compact stacked assembly perimeter bounds an area that is between about 0.1 mm^2 to about 10 cm^2 and the stacked assembly has a thickness that is between about 0.1 mm to about 10 mm.

32. The mass spectrometer of any of Claims 22-29, wherein the compact stacked

assembly comprises between 7-100 stacked conductive and insulating layers that form the mass analyzer, ionizer and detector.

33. The mass spectrometer of any of Claims 22-29, wherein the compact stacked assembly further comprises at least one planar grid and at least one planar lens assembly.

34. The mass spectrometer of any of Claims 22-29, wherein the mass analyzer comprises an ion trap, wherein the at least one planar electrode of the detector is a Faraday cup electrode that comprises a conductive layer in a shaped pattern of conductive regions that overlie and align with corresponding apertures in an adjacent electrode of the ion trap.

35. The mass spectrometer of Claim 34, wherein the conductive layer comprises a single trace or strip that connects each conductive region to an electronic collector.

36. The mass spectrometer of any of Claims 22-35, wherein the ionizer comprises a pair of planar conductors that define electrodes separated by an insulator.

37. The mass spectrometer of any of Claims 22-35, wherein the mass analyzer comprise an ion trap, and wherein a first electrode of the ion trap defines one of the at least one planar electrode of the ionizer.

38. The mass spectrometer of any of Claims 22-37, wherein the compact stacked assembly further comprises an Einzel lens comprising a plurality of spaced apart electrodes residing between the ionizer and the mass analyzer.

39. The mass spectrometer of Claim 38, wherein the mass analyzer is a cylindrical ion trap, wherein the Einzel lens electrodes comprise an array of lens apertures that align with corresponding apertures of the ion trap.

40. The mass spectrometer of any of Claims 22-39, wherein the compact stacked assembly further comprises at least one planar grid that resides between either (i) the mass analyzer and the detector or (ii) the mass analyzer and the ionizer.

41. The mass spectrometer of any of Claims 22-40, wherein the mass analyzer

comprises a CIT.

42. The mass spectrometer of Claim 41, wherein the CIT comprises concentric arrays of apertures.

43. The mass spectrometer of Claim 44, wherein the CIT comprises at least one mesh endcap.

44. The mass spectrometer of any of Claims 22-43, wherein the detector at least one planar conductor includes a conductor on an integrated circuit amplifier.

45. The mass spectrometer of any of Claims 22-44, wherein the mass analyzer is a mass analyzer array, the ionizer is an ionizer array and the detector is a detector array.

46. The mass spectrometer of any of Claims 22-45, wherein one of the at least one ionizer planar conductor is configured to cooperate with the detector to define a collection electrode for a Faraday cup associated with the detector.

47. The mass spectrometer of any of Claims 22-46, wherein the mass spectrometer is configured so that the ionizer, mass analyzer and detector operate at near isobaric conditions and at a pressure that is greater than 100 mTorr.

48. A method of fabricating an assembly for a mass spectrometer system, comprising:
providing a mass analyzer comprising a planar electrode assembly;
providing a detector comprising a planar conductor;
providing an ionizer comprising at least one planar conductor; and
stacking the mass analyzer electrode assembly, the detector and the ionizer together to form a stacked integral assembly having a perimeter that bounds an area between 0.01 mm^2 to 25 cm^2 and a stack thickness of between about 0.1 mm to about 25 mm.

49. The method of Claim 48, wherein the compact stacked assembly comprises between 7-100 stacked conductive and insulating layers that form the mass analyzer, ionizer and detector.

50. The method of Claim 48 or 49, wherein the mass analyzer is an ion trap that comprises a high density of through apertures with centers of adjacent apertures spaced apart between about 1 μm to about 5000 μm.

51. The method of any of Claims 48-50, further comprising providing an Einzel lens and placing the Einzel lens between the ionizer and the mass analyzer during the stacking of the integral assembly.

52. The method of any of Claims 48-51, wherein the detector planar conductor is a thin conductive film on a substrate, and wherein the providing the detector step comprises orienting the thin conductive film to face an endcap electrode of the mass analyzer for the stacking.

53. The method of any of Claims 48-52, further comprising providing at least one planar grid and placing the at least one planar grid between the ionizer and the mass analyzer and/or between the mass analyzer and the detector for the stacking step.

54. The method of any of Claims 48-53, wherein the detector at least one planar conductor can include or be a conductor on an integrated circuit amplifier.

55. The method of any of Claims 48-53, wherein the mass analyzer comprises a CIT with concentric arrays of apertures, the method further comprising aligning the apertures before or during the stacking step.

56. The method of Claim 55, wherein the CIT comprises at least one mesh endcap.

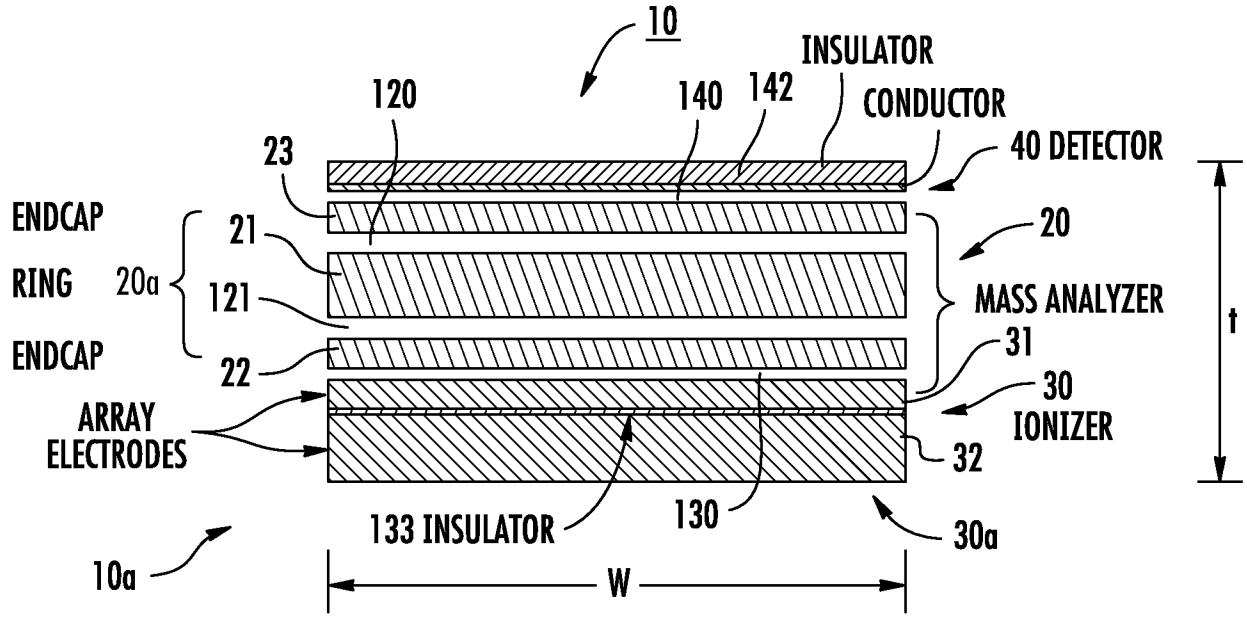

10
INSULATOR
120
140
142
CONDUCTOR
23
40 DETECTOR
ENDCAP
21
20
RING
20a
121
MASS ANALYZER
ENDCAP
22
31
30
ARRAY
ELECTRODES
IONIZER
32
133 INSULATOR
130
30a
10a
W
t

FIG. 1A

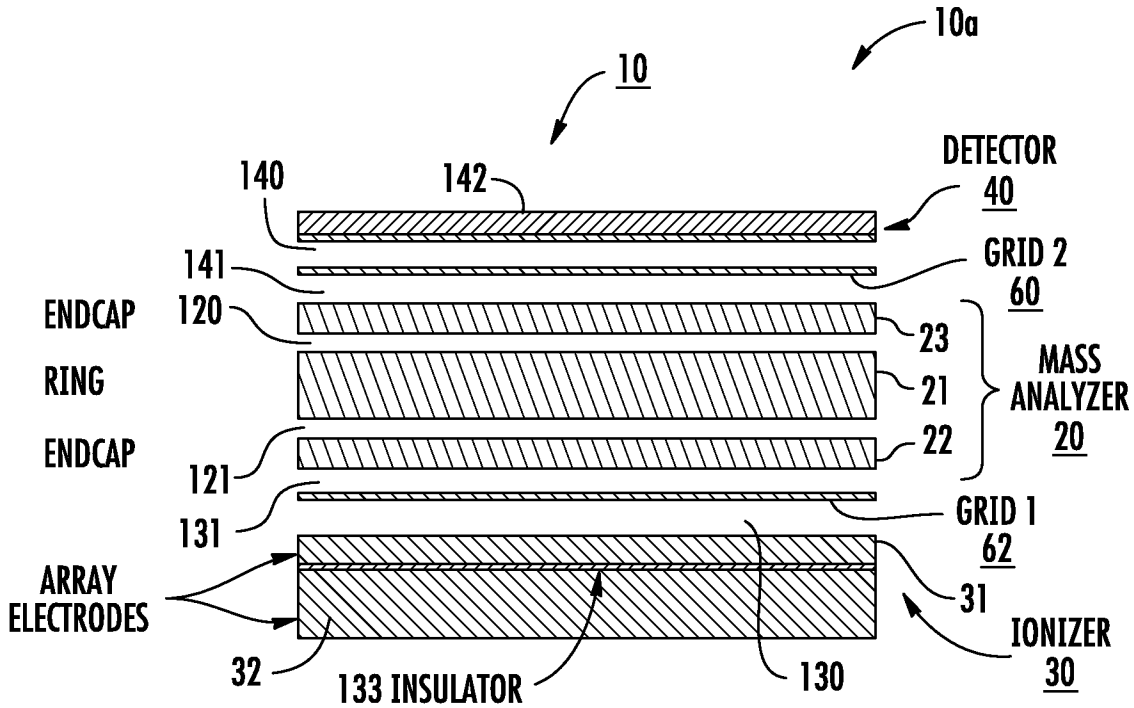

10a
10
DETECTOR
40
140
142
GRID 2
60
141
ENDCAP
120
23
RING
21
MASS
ANALYZER
20
ENDCAP
22
121
GRID 1
62
131
ARRAY
ELECTRODES
31
IONIZER
30
32
133 INSULATOR
130

FIG. 1B

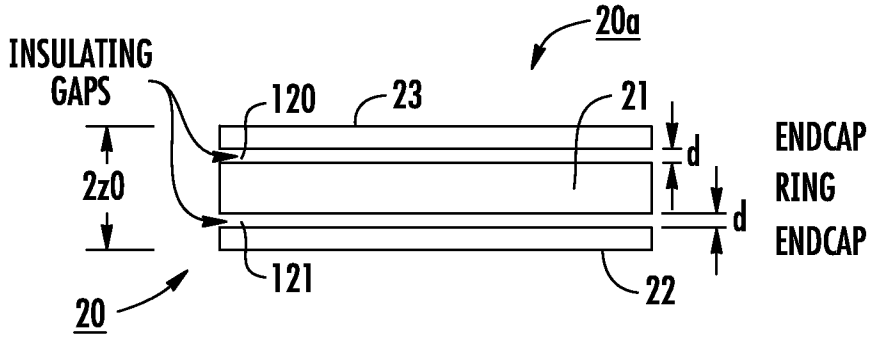


FIG. 2A

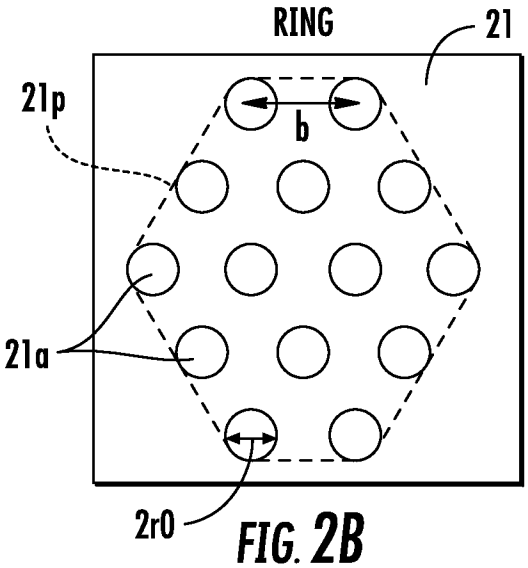


FIG. 2B

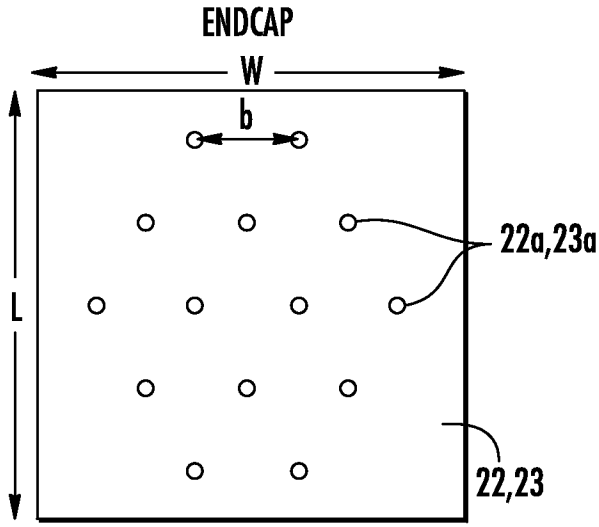


FIG. 2C

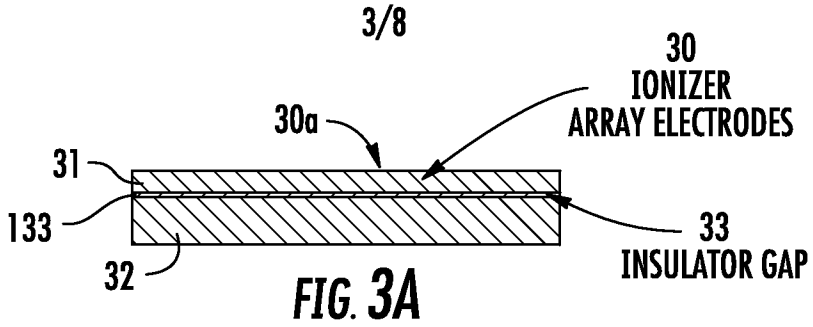


FIG. 3A

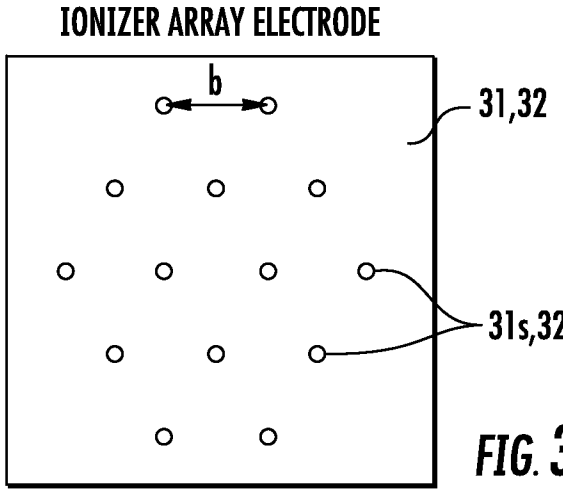


FIG. 3B

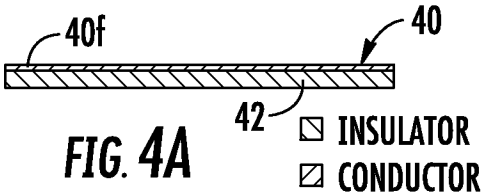


FIG. 4A

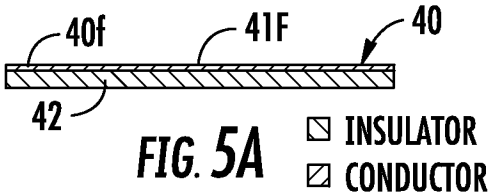


FIG. 5A

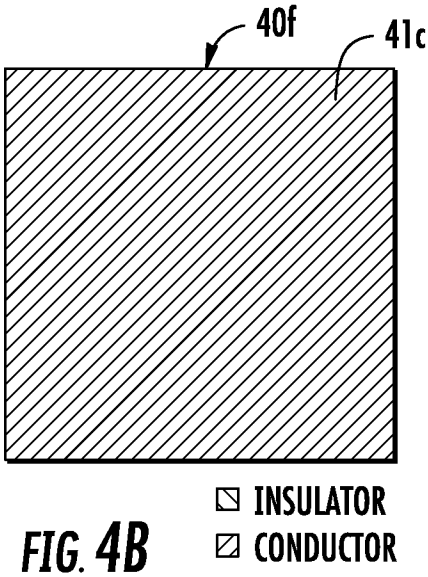


FIG. 4B

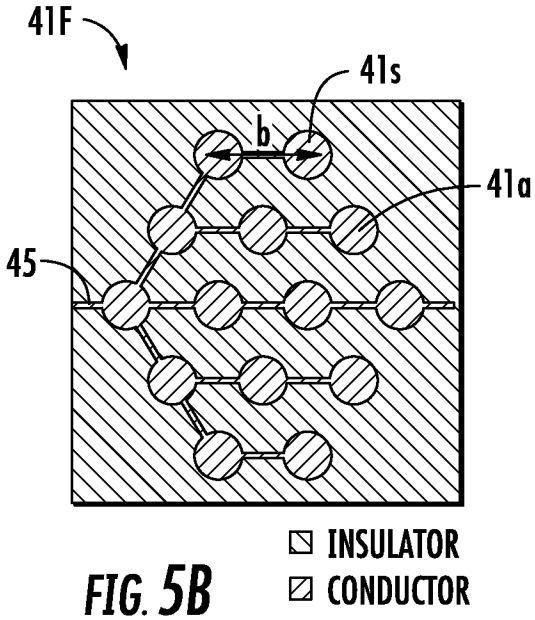


FIG. 5B

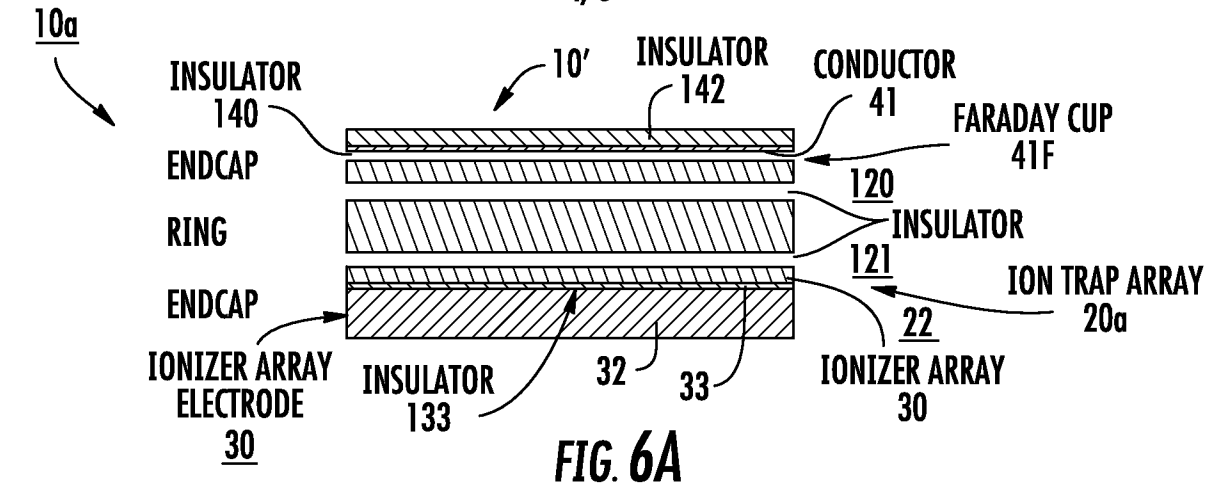


FIG. 6A

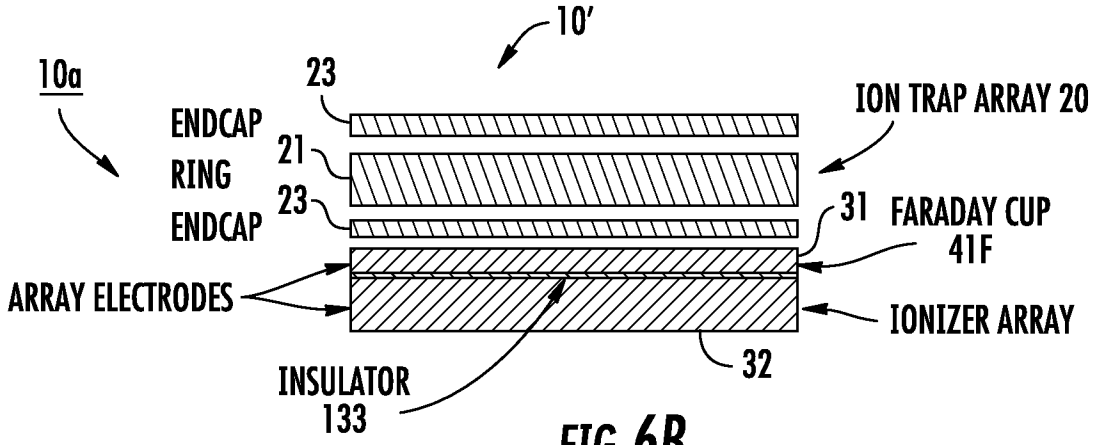


FIG. 6B

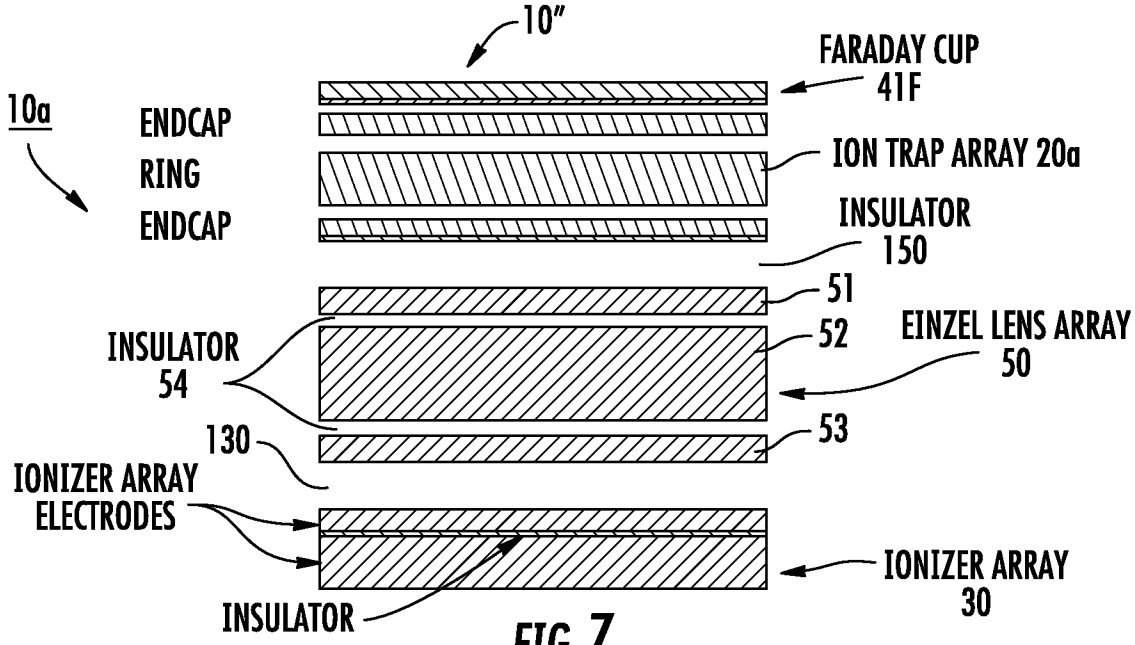


FIG. 7

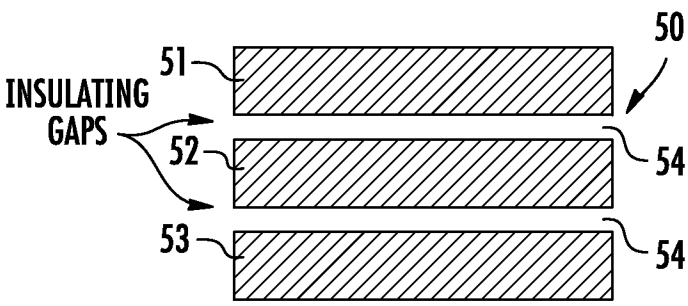


FIG. 8A

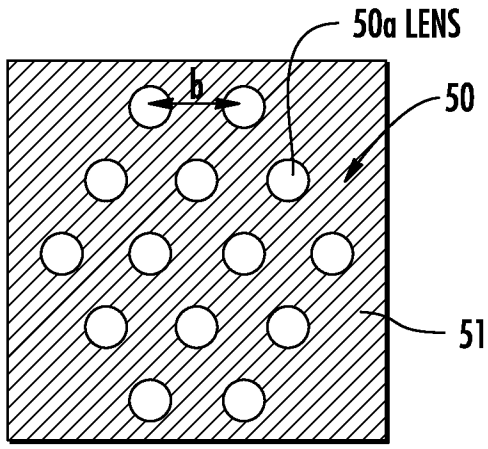


FIG. 8B

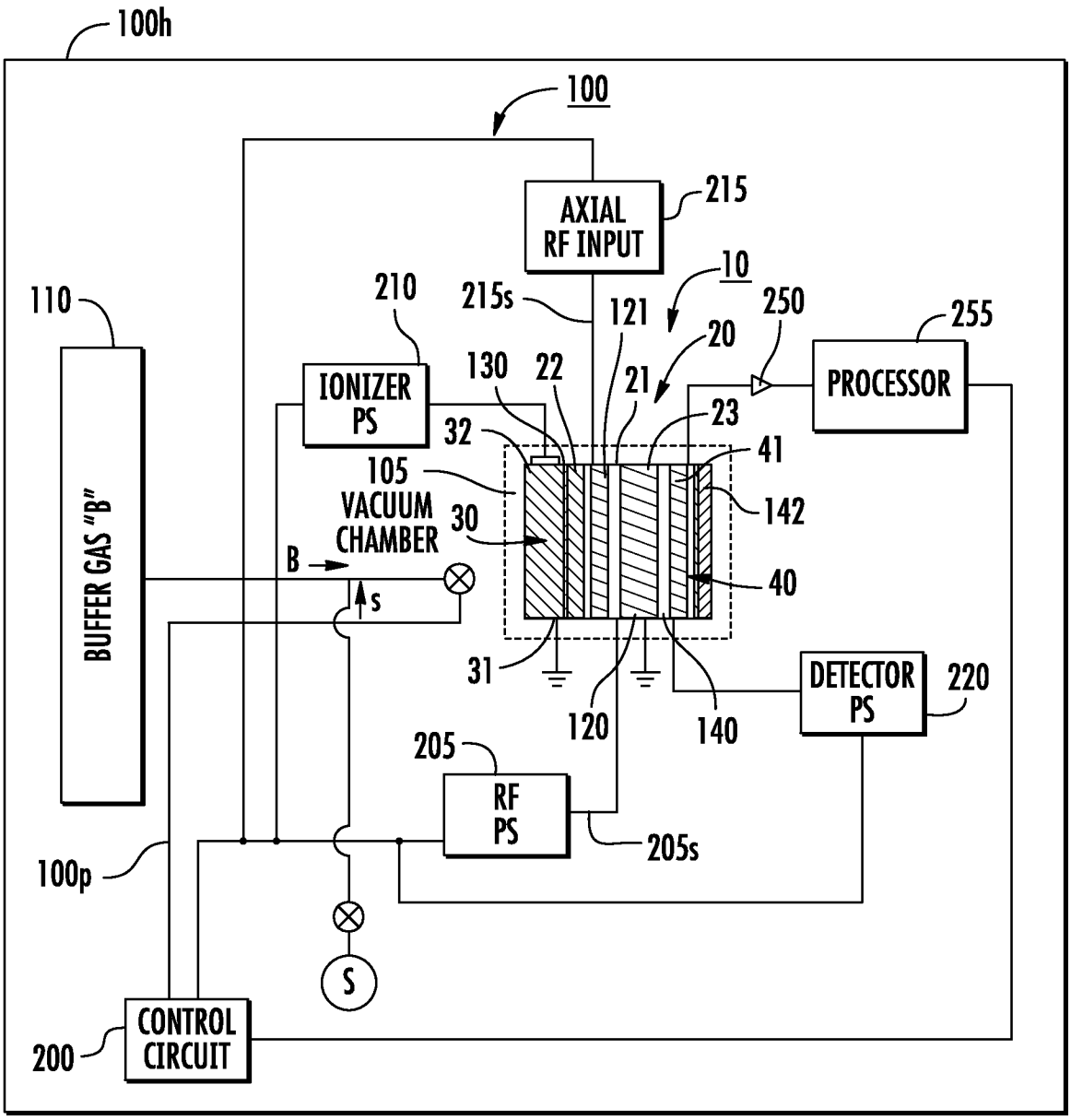


FIG. 9

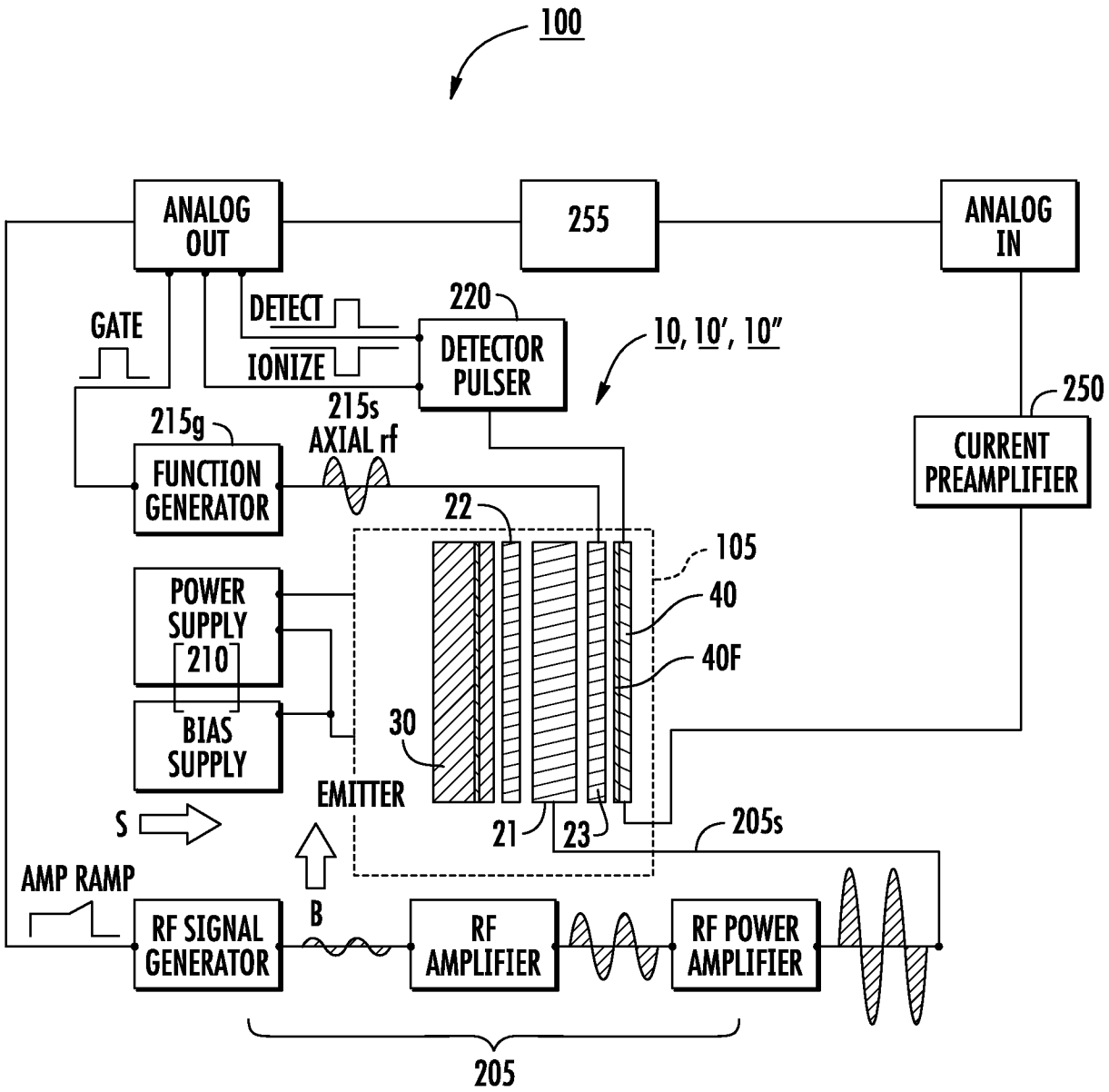

100
ANALOG OUT
255
ANALOG IN
GATE
DETECT
IONIZE
220
DETECTOR PULSER
10, 10', 10"
250
CURRENT PREAMPLIFIER
215g
FUNCTION GENERATOR
215s
AXIAL rf
22
105
40
40F
POWER SUPPLY 210
BIAS SUPPLY
30
EMITTER
S
21
23
205s
AMP RAMP
RF SIGNAL GENERATOR
B
RF AMPLIFIER
RF POWER AMPLIFIER
205

FIG. 10

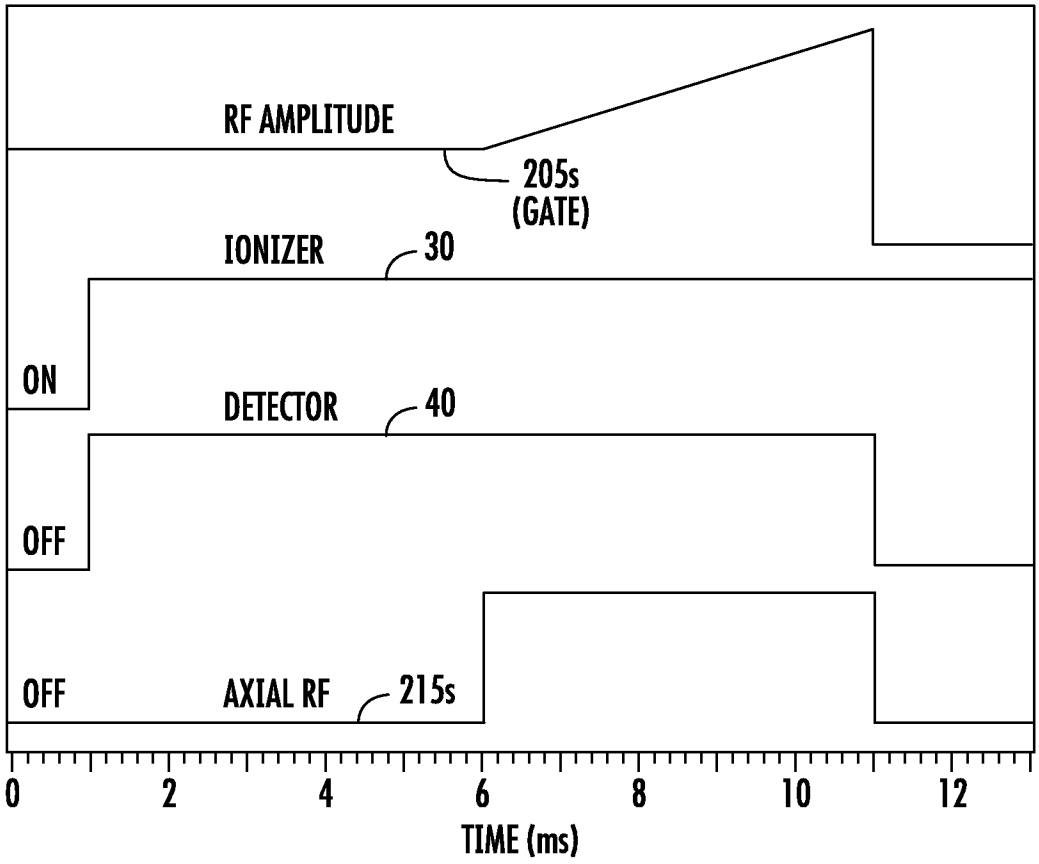

RF AMPLITUDE
205s
(GATE)
IONIZER
30
ON
DETECTOR
40
OFF
OFF
AXIAL RF
215s
0
2
4
6
8
10
12
TIME (ms)

FIG. 11

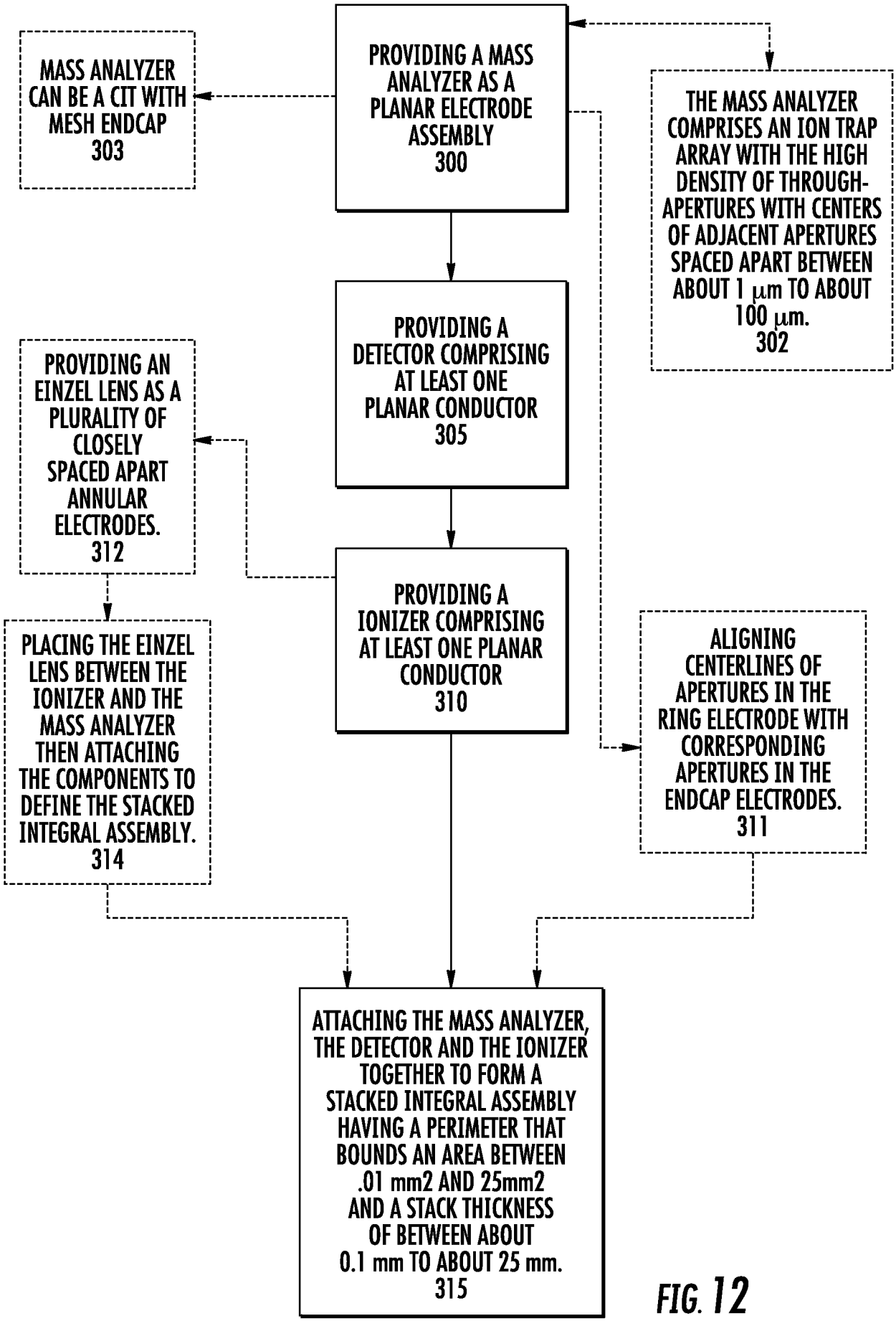

PROVIDING A MASS ANALYZER AS A PLANAR ELECTRODE ASSEMBLY 300
MASS ANALYZER CAN BE A CIT WITH MESH ENDCAP 303
THE MASS ANALYZER COMPRISES AN ION TRAP ARRAY WITH THE HIGH DENSITY OF THROUGH-APERTURES WITH CENTERS OF ADJACENT APERTURES SPACED APART BETWEEN ABOUT 1 μm TO ABOUT 100 μm. 302
PROVIDING A DETECTOR COMPRISING AT LEAST ONE PLANAR CONDUCTOR 305
PROVIDING AN EINZEL LENS AS A PLURALITY OF CLOSELY SPACED APART ANNULAR ELECTRODES. 312
PROVIDING A IONIZER COMPRISING AT LEAST ONE PLANAR CONDUCTOR 310
PLACING THE EINZEL LENS BETWEEN THE IONIZER AND THE MASS ANALYZER THEN ATTACHING THE COMPONENTS TO DEFINE THE STACKED INTEGRAL ASSEMBLY. 314
ALIGNING CENTERLINES OF APERTURES IN THE RING ELECTRODE WITH CORRESPONDING APERTURES IN THE ENDCAP ELECTRODES. 311
ATTACHING THE MASS ANALYZER, THE DETECTOR AND THE IONIZER TOGETHER TO FORM A STACKED INTEGRAL ASSEMBLY HAVING A PERIMETER THAT BOUNDS AN AREA BETWEEN .01 mm2 AND 25mm2 AND A STACK THICKNESS OF BETWEEN ABOUT 0.1 mm TO ABOUT 25 mm. 315

FIG. 12

INTERNATIONAL SEARCH REPORT

International application No.
PCT/US2014/019289

A. CLASSIFICATION OF SUBJECT MATTER

H01J 37/26(2006.01)i

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
H01J 37/26; H05F 3/04; G01N 27/62; H01T 23/00; B01D 59/44; H01J 49/42; H01J 49/00; H01T 2300; G01N 30/02

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched
Korean utility models and applications for utility models
Japanese utility models and applications for utility models

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)
eKOMPASS(KIPO internal) & Keywords: compact, mass, spectrometry, analyzer, thickness

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X Y	US 2005-0189488 A1 (CHIEN-SHING PAI et al.) 01 September 2005 See paragraphs [0009], [0011], [0027], [0030], [0031], [0036], [0045], [0054], [0056], [0057], [0064], [0072]; claims 1, 2; and figures 1, 2, 5-7, 8A-8C.	1-11,16-17,20-24,26,29-32,34-37,43,45-46,48-50,56 12-15,18-19,25,27-28,33,38-42,44,47,51-55
Y	US 6031379 A (SHINICHI TAKADA et al.) 29 February 2000 See abstract; column 1, line 65 - column 2, line 3; and figures 1-4.	12-13,38-39,51
Y	US 6850403 B1 (PETER GEFTER et al.) 01 February 2005 See abstract; and claim 2.	14,15,33,40,53
Y	WO 2009-148711 A1 (RAYTHEON COMPANY) 10 December 2009 See abstract; claim 1; and paragraphs [0004], [0023].	18,25,44,47,54
Y	US 7161142 B1 (GARTH E. PATTERSON et al.) 09 January 2007 See column 2, lines 3-4; column 7, lines 4-8; and figure 6.	19,28,41,42,55
Y	US 6351983 B1 (JEFFREY S. HAAS et al.) 05 March 2002 See abstract; and claim 1.	27,52

☐ Further documents are listed in the continuation of Box C.

☒ See patent family annex.

* Special categories of cited documents:
"A" document defining the general state of the art which is not considered to be of particular relevance
"E" earlier application or patent but published on or after the international filing date
"L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)
"O" document referring to an oral disclosure, use, exhibition or other means
"P" document published prior to the international filing date but later than the priority date claimed
"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone
"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents,such combination being obvious to a person skilled in the art
"&" document member of the same patent family

Date of the actual completion of the international search	Date of mailing of the international search report
15 July 2014 (15.07.2014)	**16 July 2014 (16.07.2014)**

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Authorized officer
KIM, Do Weon
Telephone No. +82-42-481-5560

Form PCT/ISA/210 (second sheet) (July 2009)

INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No.
PCT/US2014/019289

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